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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.		
10/684,502	10/15/2003	Tomoyo Yamaguchi	244071US2	4605		
22850	7590 09/30/2005		EXAMINER			
OBLON, SPIVAK, MCCLELLAND, MAIER & NEUSTADT, P.C.			CHEN, KIN-CHAN			
1940 DUKE			ART UNIT	PAPER NUMBER		
ALEXAND	RIA, VA 22314					
			1765			
				DATE MAILED: 09/30/2005		

Please find below and/or attached an Office communication concerning this application or proceeding.

	Application No.	Applicant(s)	-4/		
	10/684,502	YAMAGUCHI, TOMOY	′o		
Office Action Summary	Examiner	Art Unit			
	Kin-Chan Chen	1765			
The MAILING DATE of this communication app Period for Reply	pears on the cover sheet with the c	orrespondence addres	s		
A SHORTENED STATUTORY PERIOD FOR REPLY WHICHEVER IS LONGER, FROM THE MAILING DA Extensions of time may be available under the provisions of 37 CFR 1.1 after SIX (6) MONTHS from the mailing date of this communication. If NO period for reply is specified above, the maximum statutory period of Failure to reply within the set or extended period for reply will, by statute Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	ATE OF THIS COMMUNICATION 35(a). In no event, however, may a reply be tim will apply and will expire SIX (6) MONTHS from a cause the application to become ABANDONE	J. nely filed the mailing date of this commun O (35 U.S.C. § 133).	·		
Status					
1) Responsive to communication(s) filed on 17 A 2a) This action is FINAL. 2b) This 3) Since this application is in condition for alloward closed in accordance with the practice under E	s action is non-final. nce except for formal matters, pro		rits is		
Disposition of Claims					
4) Claim(s) 1-3 and 5-29 is/are pending in the application Papers 9) The specification is objected to by the Examine 10) The drawing(s) filed on is/are: a) according are subjected to the Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Examine 10. The oath or declaration is objected to by the Examine 10. The oath or declaration is objected to by the Examine 10. The oath or declaration is objected to by the Examine 11. The oath or declaration is objected to by the Examine 11. The oath or declaration is objected to by the Examine 11. The oath or declaration is objected to by the Examine 11. The oath or declaration is objected to by the Examine 11. The oath or declaration is objected to by the Examine 11. The oath or declaration is objected to by the Examine 11.	wn from consideration. r election requirement. er. epted or b) objected to by the Edrawing(s) be held in abeyance. Seetion is required if the drawing(s) is objected.	e 37 CFR 1.85(a). ected to. See 37 CFR 1.			
Priority under 35 U.S.C. § 119	•				
 12) Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f). a) All b) Some * c) None of: 1. Certified copies of the priority documents have been received. 2. Certified copies of the priority documents have been received in Application No 3. Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)). * See the attached detailed Office action for a list of the certified copies not received. 					
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date	4) Interview Summary Paper No(s)/Mail Da 5) Notice of Informal Pa)		

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DETAILED ACTION

Claim Rejections - 35 USC § 102

1. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(a) the invention was known or used by others in this country, or patented or described in a printed publication in this or a foreign country, before the invention thereof by the applicant for a patent.

Claim Rejections - 35 USC § 103

- 2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 3. Claims 1, 2, 5, and 28 are rejected under 35 U.S.C. 102(a) as anticipated by or, in the alternative, under 35 U.S.C. 103(a) as obvious over Nishizawa (US 6,617,244).

In a method for plasma treatment, Nishizawa (col. 5, lines 58-60; col. 6, lines 53-55; Fig. 2B) teaches that a substrate including a SiC layer and a SiO₂ layer may be arranged in a chamber. An etching gas may be introduced into the chamber. The SiC layer may be plasma etched. The etching gas may include CHF₃. SiO₂ may be a mask

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layer on the SiC layer. The base layer of the SiC layer may be a Cu layer. The etching gas may include nitrogen. Since Nishizawa teaches that "a fluorocarbon" such as CHF₃ may be used to etch SiC (col. 3, line 37; col. 6, line 54). Therefore, it is considered to reads on applicant's "as a main fluorocarbon component thereof".

4. Claims 8, 18, 19, 20, and 29 are rejected under 35 U.S.C. 103(a) as being unpatentable over Nishizawa (US 6,617,244).

In a method for plasma treatment, Nishizawa (col. 5, lines 58-60; col. 6, lines 53-55; Fig. 2B) teaches that a substrate including a SiC layer and a SiO₂ layer may be arranged in a chamber. An etching gas may be introduced into the chamber. The SiC layer may be plasma etched. The etching gas may include CHF₃. The etching gas may include nitrogen. The etching gas may also include the inert gas (e.g., argon). Since Nishizawa teaches that "a fluorocarbon" such as CHF₃ may be used to etch SiC (col. 3, line 37; col. 6, line 54). Therefore, it is considered to reads on applicant's "as a main fluorocarbon component thereof". Nishizawa teaches that in the case of the fluorine compound, when an excess amount of organic polymer is not generated in etching, the mixture of the oxygen gas is not required (col. 6, lines 65-67). Nishizawa discloses that the fluorine compound may be fluorocarbon such as CHF₃ (col. 3, lines 38-42). Furthermore, since Nishizawa uses same etching gas (CHF₃) for etching same material (SiC) as instantly claimed, it would result in the same amount of organic polymer generated. Therefore, the oxygen gas is not required in the etching gas as instantly

claimed because the organic polymer being generated is considered not to be an excess amount.

5. Claims 3, 6, 7, 9-17, and 21-27 are rejected under 35 U.S.C. 103(a) as being unpatentable over Nishizawa (US 6,617,244) as evidenced by Li et al. (US 6,670,278, Nemani et al. (US 6,764,958), Chooi et al. (US 6,284,657) and Demmin (US 6,635,185).

In a method for plasma treatment, Nishizawa (col. 5, lines 58-60; col. 6, lines 53-55; Fig. 2B) teaches that a substrate including a SiC layer and a SiO₂ layer may be arranged in a chamber. An etching gas may be introduced into the chamber. The SiC layer may be plasma etched. The etching gas may include CHF₃. The etching gas may include nitrogen. The etching gas may also include the inert gas (e.g., argon). Since Nishizawa teaches that "a fluorocarbon" such as CHF₃ may be used to etch SiC (col. 3, line 37; col. 6, line 54). Therefore, it is considered to reads on applicant's "as a main fluorocarbon component thereof". Nishizawa teaches that in the case of the fluorine compound, when an excess amount of organic polymer is not generated in etching, the mixture of the oxygen gas is not required (col. 6, lines 65-67). Nishizawa discloses that the fluorine compound may be fluorocarbon such as CHF₃ (col. 3, lines 38-42). Furthermore, since Nishizawa uses same etching gas (CHF₃) for etching same material (SiC) as instantly claimed, it would result in the same amount of organic polymer generated. Therefore, the oxygen gas is not required in the etching gas as instantly

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claimed because the organic polymer being generated is considered not to be an excess amount.

Claims 3, 12-14, 17, 21, 24, and 25 disclose various layers structures above or below the SiC layers. They are well-known features and merely choices of design, depending on the product requirement. See Li et al. (US 6,670,278; col. 4, lines 63 through col. 5, line 1), Nemani et al. (US 6,764,958; col. 7,line 44 through col. 8, line 59), Chooi et al. (US 6,284,657; col. 7, line 52 through col. 8, line 10) in the record as evidence.

The above-cited claims differ from prior art by specifying various compositions and processing parameters (such as ratios of flow rates of etchants in claims 6, 7, 9-11,15, and 16). However, same were known to be result effective variables and commonly determined by routine experiment. The process of conducting routine experimentations so as to produce an expected result is obvious to one of ordinary skill in the art. In the absence of showing criticality, it is the examiner's position that a person having ordinary skill in the art at the time of the claimed invention would have found it obvious to modify prior art by performing routine experiments by using various compositions and different processing parameters to obtain optimal result. See Demmin (US 6,635,185) in the record as evidence.

Response to Arguments

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6. Applicant's arguments with respect to claims 1-29 have been considered but are most in view of the new ground(s) of rejection.

Conclusion

7. The prior art made of record and not relied upon is considered pertinent to applicant's disclosure.

Demmin (US 6,635,185; Col. 7, lines 5-25) teaches that one skilled in the art of plasma etching and cleaning may vary type of plasma etching (RIE, HDP, plasma etching..), composition, flow rate, temperature, pressure, power, time, bias accordingly to etch a desired material satisfactorily.

Li et al. (US 6,670,278; col. 4, lines 63 through col. 5, line 1), Nemani et al. (US 6,764,958; col. 7,line 44 through col. 8, line 59), and Chooi et al. (US 6,284,657; col. 7, line 52 through col. 8, line 10) disclose various layers structures above or below the SiC layers.

8. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within

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TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

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9. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Kin-Chan Chen whose telephone number is (571) 272-1461. If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Nadine Norton can be reached on (571) 272-1465. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306. Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

September > 7, 2005

Kin-Chan Chen Primary Examiner Art Unit 1765